

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

ATTORNEY DOCKET NO. MI22-2308

SERIAL NO. 10/615, 051

APPLICANT: Brian A. Vaarstra

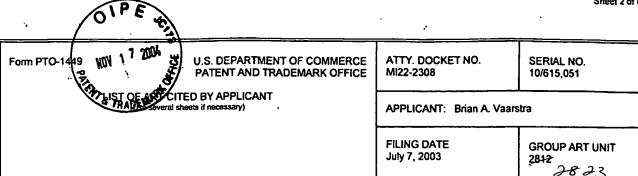
FILING DATE July 7, 2003

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"Examiner's Initials		Document Number	Date .	Name	Class	Subclass	Filing Date If Appropriate
BX	*	3,990,927	11/1976	Montier			
BK	AB	4,474,975	10/1984	Clemons et al.	,		
Bu	AC	5,156,881	10/1992	Okano et al.			
BIL	9	5,182,221	01/1993	Sato			
Bol	Æ	5,410,176	04/1995	Liou et al.	24	707	00
BU	AF	5,470,798	11/1995	Ouellet			
BU	AG	5,719,085	02/1998	Moon et al.		<u> </u>	
BR	AH.	5,741,740	04/1998	Jang et al.			
BK	A	5,776,557	07/1998	Okano et al.			

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		Document Number	Date	Country	Class	Subclass	Translation	
		Number					Yes	No
Bu	~	02277253A	11/1990	Japan (Hayashide et al.)			Abstract	
	AK ,	146224	01/1996	Japan				_
BU	AL	06-334031	12/1994	Japan			Abstract	

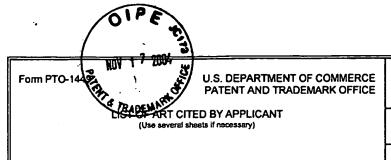
OTHER RE	FEREN	ICES (including Author, Title, Date, Pertinent Pages, Etc.)
	AM	Beekmann et al., Sub-micron Gap Fill and In-Situ Planarisation using Flowfill™ Technology, Electrotech 1-7
BU		ULSI Conference, Portland, OR (October 1995).
	AN	Horie et al., Kinetics and Mechanism of the Reactions of O(3P) with SiH4, CH3SiH3, (CH3)2SiH2, and
BR		(<i>CH</i> ₃) ₃ SiH, 95 J. Phys. Chem 4393–4400 (1991).
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Bu	*	5,786,039	07/1998	Brouquet	1		
BR	AB	5,801,083	09/1998	Yu et al.			
BR	AC	5,863,827	01/1999	Joyner			
Ba	9	5,883,006	03/1999	lba	A -7 /	, x v	7
BU	Æ	5,888,880	03/1999	Gardner et al. EV3 (&	8	לא ל	0
BU	*	5,895,253	04/1999	Akram			\
BU	AG	5,904,540	05/1999	Sheng et al.			\ .
·BU	Æ	5,930,645	07/1999	Lyons et al.			
BU	Z	5,943,585	08/1999	May et al.			. j.

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	AM	Kiermasz et al., Planarisation for Sub-Micron Devices Utilising a New Chemistry, Electrotech 1-2, DUMIC
be		Conference, California (February 1995):
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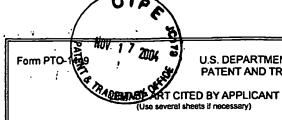
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BK	*	5,950,094	09/1999	Lin et al.			
BK	AB	5,960,299	09/1999	Yew et al.			
BU	AC	5,972,773	10/1999	Liu et al.			
BU	AD	5,998,280	12/1999	Bergemont et al.	7 2	47	7700
BU	AE	6,030,881	02/2000	Papasouliotis et al.			9 ' 00
BU	· AF	6,051,477	04/2000	Nam			
BN	· AG	6,156,674	12/2000	Li et al.			
BR	AH .	6,719,012	4/2004	Doan et al.	• •		_ \ ,
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BA	2	5,570,469	6/1998	Uram et al.	/		
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AN	McClatchie et al. Low Dielectric Constant Flowfill™ Technology for IMD Applications, 7 pages (pre-August 1999).
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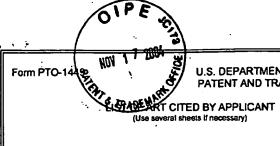
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BL	*	5,105,253	04/1992	Poliock	357	49	\ /
BU	AB	5,604,149	02/1997	Paoli et al.	437	67	
BU	AC	5,616,513	04/1997	Shepard	438	402	\
BU	. 4	5,786,263	07/1998	Perera	438	431	
BK	AE	5,895,255	04/1999	Tsuchiaki	438	427	1
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BU	AG	5,981,354	11/1999	Spikes et al.	438	424	71
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	AM	Curtis et al, "APCVD TEOS: O3 Advanced Trench Isolation Applications", Semiconductor Fabtech, 9th Ed.,
BU		p. 241 - 247
	AN	George, S:M-et-al., "Atomic layer controlled deposition of SiO ₂ and Al ₂ O ₃ using ABAB binary reaction
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,	AO	Morishita et al. "Atomic-layer chemical-vapor-deposition of silicon-nitride", Applied Surface Science 112,
BU		Elsevier Science B.V., 1997, p. 198-204.
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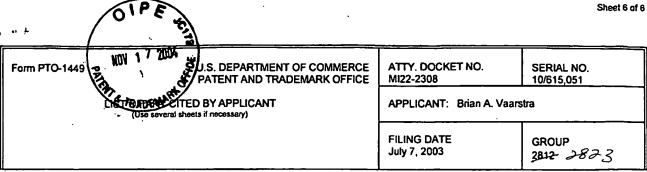
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PN.	*	6,090,675	07/2000	Lee et al.	438	301	Ţ
BU	AB	6,171,962	01/2001	Karlsson et al.	438	692	
BU	AC	6,187,651	02/2001	Oh	438	435	
PN	AD	6,191,002	02/2001	Koyanagi	438 、	431	Ý
BK	Æ	6,326,282	12/2001	Park et al.	438	424	
BU	AF	6,329,266	11/2001	Hwang et al.	438	424	
BU	·AG	6,355,966	03/2002	Trivedi	257	499	
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AL .	Gasser et al., "Quasi-monolayer-deposition of silicon dioxide", Elsevier Science S.A., 1994, p. 213-218.
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	J. Vac. Sci. Technol. B 13(4), Jul/Aug 1995, p. 1888-1892.
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Bol	*	6,448,150	09/2002	Tsai et al.	438	427	\ /
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APPLICANT: Brian A. Vaartstra

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